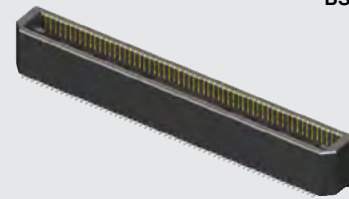


BTE-040-02-L-D-A



BTE-060-02-F-D-A

BSE-020-01-F-D-A



**BTE, BSE SERIES**

**(0.80 mm) .0315"**

# BASIC BLADE & BEAM HEADER & SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?BTE](http://www.samtec.com?BTE) or [www.samtec.com?BSE](http://www.samtec.com?BSE)

**Insulator Material:** Liquid Crystal Polymer  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50 μm (1.27 μm) Ni  
**Current Rating:** 2 A per pin (1 pin powered per row)  
**Operating Temp Range:** -55 °C to +125 °C  
**Voltage Rating:** 225 VAC with 5 mm Stack Height  
**Max Cycles:** 100  
**RoHS Compliant:** Yes

## PROCESSING

**Lead-Free Solderable:** Yes  
**SMT Lead Coplanarity:** (0.10 mm) .004" max (020-080) (0.15 mm) .006" max (100-120)  
**Board Stacking:** For applications requiring more than two connectors per board or 80 positions or higher, contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00) .197
-02	(8.00) .315

\*Processing conditions will affect mated height.

## ALSO AVAILABLE (MOQ Required)

- 30 μm (0.76 μm) Gold
- Edge Mount Capability
- Friction Lock option
- 11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)

Contact Samtec.

**Note:** Some lengths, styles and options are non-standard, non-returnable.

**BTE**

**NO. OF POSITIONS PER ROW**

**LEAD STYLE**

**PLATING OPTION**

**D**

**A**

**OTHER OPTION**

Mates with: **BSE**

**-020, -040, -060, -080, -100, -120**

Specify LEAD STYLE from chart

LEAD STYLE	A
-01	(4.27) .168
-02	(7.21) .284

**-F**  
= Gold Flash on contact, Matte Tin on tail

**-L**  
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

**-C\***  
= Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails

**-K**  
= (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad

**-TR**  
= Tape & Reel (60 positions maximum)

**\*Note:** -C Plating passes 10 year MFG testing

• Passes 10 year MFG

**BSE**

**NO. OF POSITIONS PER ROW**

**01**

**PLATING OPTION**

**D**

**A**

**OTHER OPTION**

Mates with: **BTE**

**-020, -040, -060, -080, -100, -120**

**-F**  
= Gold Flash on contact, Matte Tin on tail

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= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

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= Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails

**-TR**  
= Tape & Reel (80 positions maximum)

**\*Note:** -C Plating passes 10 year MFG testing

• Passes 10 year MFG